

S92	164	S91 and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 15:52
S93	1	S91 and ground and dielectric and ((adhesive melt\$4 bond\$3) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 16:02
S94	1	S91 and ground and (dielectric substrate) and ((adhesive melt\$4 bond\$3) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 16:17
S95	1	S91 and ground and (dielectric substrate) and ((adhesive adhesiv\$3 melt\$4 bond\$3) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 16:17
S96	20	S91 and ground and (dielectric substrate) and (adhesive adhesiv\$3 melt\$4 bond\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/04 16:54
S97	81	S91 and ground and (dielectric substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/05 11:28
S98	2	("6703114").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/05 13:51
S99	2	("6271792").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/05 13:51
S100	2	("6703114").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/09 21:41
S101	11	("4790968" "5112726" "5538789" "5541366" "5733639" "5910354" "6197407" "6356245" "6366259" "6451441" "6518514").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/02/09 21:47

S10 2	233	(dielectric substrate) and ((adhesive melt\$4 bond\$3) near layer) and ((radiat\$4 adj3 element) antenna) and antenna and patch and ground	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/10 10:07
S10 3	1	("20060017616").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/02/10 10:05
S10 4	197	(dielectric substrate) and ((adhesive melt\$4 bond\$3) near layer) and ((radiat\$4 adj3 element) antenna) and antenna and patch and ground and @ad <"20040722"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/11 15:19